## PATENT ASSIGNMENT COVER SHEET

# Electronic Version v1.1 Stylesheet Version v1.2

## EPAS ID: PAT2613489

SUBMISSION TYPE:			NEW ASSIGNMENT			
NATURE OF CONVEY	ANCE:		ASSIGNMENT			
CONVEYING PARTY	DATA		·			
		N	lame	Execution Date		
DEXTER CORPORAT	ΓΙΟΝ			08/23/2000		
RECEIVING PARTY D	ΑΤΑ					
Name:	LOCTITE CO	DRPOR	ATION			
Street Address: 1001 TROUT BROOK CROSSING						
City: ROCKY HILL						
State/Country:						
PROPERTY NUMBERS Total: 1						
Property Type Number						
Patent Number: 5718941					. 76	
CORRESPONDENCE	DATA				14041	
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Correspondence will be sent via US Mail when the email attempt is unsuccessful.						
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Address Line 4: ROCKY HILL, CONNECTICUT 06067						
ATTORNEY DOCKET NUMBER: ASSIGNMENT PROJECT						
NAME OF SUBMITTE	R:		THERESA DOONAN			
Signature:			/Theresa Doonan/			
Date:			11/13/2013			
				PATENT		

### Total Attachments: 10

source=Dexter\_Corporation\_to\_LOCTITE\_ASSIGNMENT#page1.tif source=Dexter\_Corporation\_to\_LOCTITE\_ASSIGNMENT#page2.tif source=Dexter\_Corporation\_to\_LOCTITE\_ASSIGNMENT#page3.tif source=Dexter\_Corporation\_to\_LOCTITE\_ASSIGNMENT#page5.tif source=Dexter\_Corporation\_to\_LOCTITE\_ASSIGNMENT#page5.tif source=Dexter\_Corporation\_to\_LOCTITE\_ASSIGNMENT#page6.tif source=Dexter\_Corporation\_to\_LOCTITE\_ASSIGNMENT#page7.tif source=Dexter\_Corporation\_to\_LOCTITE\_ASSIGNMENT#page8.tif source=Dexter\_Corporation\_to\_LOCTITE\_ASSIGNMENT#page8.tif source=Dexter\_Corporation\_to\_LOCTITE\_ASSIGNMENT#page9.tif source=Dexter\_Corporation\_to\_LOCTITE\_ASSIGNMENT#page10.tif

### PATENT ASSIGNMENT

WHEREAS, Dexter Corporation (hereinafter, "Assignor"), a corporation of the State of Connecticut, having its principal business address at 1 Elm Street, Windsor Locks, Connecticut 06096-2334, U.S.A., is the owner of all rights in the patents and patent applications set forth on the attached <u>Schedule A</u>, and the inventions disclosed and claimed therein; and

WHEREAS, Loctite Corporation (hereinafter, "Assignee"), a Delaware corporation, having its principal business address at 1001 Trout Brook Crossing, Rocky Hill, Connecticut 06067, USA, desires to acquire the entire right, title, and interest in and to said inventions, patents and patent applications;

NOW THEREFORE, effective immediately by this document (the "Assignment"), and for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, Assignor does hereby sell, assign, transfer and set over to Assignee, for its own use and enjoyment, and for the use and enjoyment of its successors, assigns and other legal representatives, as fully and entirely as the same would have been held and enjoyed by Assignor if this Assignment had not been made, the entire right, title, and interest in the United States and in all foreign countries and jurisdictions, in the patents and patent applications identified in the attached <u>Schedule A</u>, as well as to the inventions disclosed and claimed therein, and all continuations, divisions, reissues, reexaminations, corrections, substitutes, extensions or foreign equivalents thereof, (collectively, "Patents") and including without limitation the subject matter of all claims which may be obtained thereform.

### PATENT REEL: 031593 FRAME: 0314

rights of priority under International Convention for the Protection of Industrial Property, the Inter-American Convention Relating to Patents, Design and Industrial Models, and any other international agreements to which the United States adheres; together with all income, royalties, damages, claims and payments now or hereafter due or payable with respect thereto, and in and to all causes of action (either in law or in equity) and the right to sue, counterclaim, and recover for any and all legal and equitable claims for past, present and/or future infringement, damages, or other unauthorized use of the rights assigned to Assignee hereunder.

Assignor authorizes and requests the U.S. Patent and Trademark Office, or any foreign equivalent thereto, to record Assignee as owner of the Patents, and to issue any and all letters patent of the United States, or any other country, thereon to Assignee, as assignee of the entire, title and interest in, to and under the same, for the sole use and enjoyment of Assignee, its successors, assigns or other legal representative.

Assignor hereby agrees to provide cooperation and assistance to, and to execute any papers and to perform such other proper acts as Assignee, or its successors, assigns or other legal representative, may deem reasonably necessary to secure to Assignee or to its successors or assigns, the rights hereby transferred and to maintain the full value of such rights; provided, however, that the provision of the foregoing cooperation and assistance by Assignor shall be at the sole expense of Assignee.

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In addition, to the extent that Assignee identifies additional Patents that are part of the Business (as defined in the Asset Purchase Agreement between Dexter Corp. and Loctite Corp. dated as of June 20, 2000), Assignor agrees to execute additional assignment agreements in forms substantially similar to this Assignment, to transfer the entire right, title and interest in such Patents to Assignee.

This Assignment may be executed in counterparts, each of which shall be deemed an original, but all of which together shall constitute one and the same instrument.

WHEREFORE, Assignor and Assignee have caused this Patent Assignment to be duly executed below, on the dates indicated, by their duly authorized officers.

DEXTER CORPORATION ("Assignor")

H Sall By: Mon Print Name! Vice President Title: V. Aujust 23,2000 Date: 81 By: Print Name: Title: Date:

LOCTITE CORPORATION ("Assignee")

merkel

Title: V.P.Date: 8/23/00

### STATE OF NEW YORK ) ) SS.: COUNTY OF NEW YORK )

On this  $23^{\text{R}}$  day of <u>Aug-us</u>, 2000, before me a Notary Public in and for the County of <u>NEW YORK</u> in the State of <u>NEW YORK</u>, personally appeared <u>BRUCE H. BEATT</u>, to me known to be the <u>VICE PRESIDENT</u> of Dexter Corporation, and being duly

sworn, averred that, being duly authorized, (s)he executed the foregoing Assignment

as the free act and deed of said corporation for the uses and purposes set forth.

SS.:

Notary Public g. Straid

INCOUELINE Y GIRARD NOTARY PUBLIC, State of New York No. 01GI5021753 Qualified in New York County Commission Expires Dec. 20, 1999

Commission Expires Dec. 20, 1999 2001 My Commission expires:

STATE OF NEW YORK ) ) COUNTY OF NEW YORK )

On this 23% day of <u>August</u>, 2000, before me a Notary Public in and for the County of <u>NEW YORK</u> in the State of <u>NEW YORK</u>, personally appeared <u>STEPHERN MERKEL</u>, to me known to be the <u>VICE PRESTOR</u> of Loctite Corporation, and being duly sworn, averred that, being duly authorized, (s)he executed the foregoing Assignment

as the free act and deed of said corporation for the uses and purposes set forth.

Sotar Public y. Scracd

JACQUELINE Y GIRARD NOTARY PUBLIC, State of New York No. 01GI5021753 Qualified in New York County Commission Expires Dec. 20, 1999

My Commission expires: \_\_\_\_\_

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### PATENT REEL: 031593 FRAME: 0317

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	Patent No.	<b>Jane or Alling</b>	Status (Blank = Active)		Current
Compositions Comprising Capsules for Varying Tack	60/090007			US	Dexter
Production of "Thru Vias" in Multi-Level Printed Circuit Boards by Imprinting Technology	60/076190			Sn	Dexter
Production of "Thru Vias" in Multi-Level Printed Circuit Boards by Imprinting Technology	09/257,911			US	Dexter
Abrasion Resistant Coaling*	4,868,069	9/19/89		SA	Dexter
Adhesive Compositions with Retarding Additives	60/114941			US	Dexter
Composite Tube and Method of Manufacture	4,968,545	11/6/90		SN	Dexter
Conductive Film Composite	5,928,767	7/27/99		SU	Dexter
Corrosion Resistant Waterborne Adhesive Primers	5,260,357	11/9/93		US	Dexter
Curable Resins Compressing Gel Encapsulated Curing Agents	60/090006			SN	Dexter
Debossable Films	5,731,086	3/24/98		Sn	Dexter
Encapsulating Electronic Components	4,826,896	5/2/89		US	Dexter
Encapsulating Electronic Components*	5,158,735	10/27/92		US	Dexter
Epoxy Containing Die-Attach Compositions	5,969,036	10/19/99		US	Dexter
Expandable Films and Molded Products Therefrom	5,397,611	3/14/97		SN	Dexter
Expandable Films and Molded Products Therefrom	5,234,757	8/10/93		US	Dexter
Expandable Films and Molded Products Therefrom	5,783,272	7/21/98		Sn	Dexter

# SCHEDULE A

# UNITED STATES PATENTS

PATENT REEL: 031593 FRAME: 0318

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Tatent No.,     Issuer (HIIIng Date     Claim Acpliant     Claim Softweit     Chain Acpliant       Application No.,     Date     Acpliant     Cuaute     Acpliant     Cuaute       Application No.,     Date     Acpliant     Cuaute     Cuaute     Cuaute       5,540,963     7/30/96     Io/13/92     US     US     US       5,476,716     12/19/95     US     US     US     US       5,375,766     12/27/94     US     US     US       5,375,766     12/27/94     US     US       609/347,091     7/1/99     US     US       5,572,677     9/30/97     US     US       5,761,801     6/9/99     US     US       5,761,801     6/9/99     US     US       5,761,801     6/9/99     US     US       5,904,500     5/18/99     US     US	Dexter	US		10/26/00	5 072 166	
Patent No.     Issues or future Date     Statu Acplication No.     Issues or future Date     Statu Acplication No.       5,540,963     7/30/96     Koriveli Acplication No.     Country       5,540,963     7/30/96     US     US       5,154,976     10/13/92     US     US       5,476,716     12/19/95     US     US       5,375,766     12/17/94     US     US       5,375,766     12/17/94     US     US       5,370,921     7/1/99     US     US       5,672,677     9/30/97     US     US       5,665,461     9/9/977     US     US       5,761,801     6/9/98     US     US       5,718,789     2/17/98     US     US       4,983,552     1/8/91     US     US	Dexter	Sn		5/18/99	5,904,500	Method for the preparation of lead-on-chip assemblies
Parent No.     Issue or Friling Date     Channy Actively     Country Country       5,540,963     7/30/96     US     US       5,154,976     10/13/92     US     US       5,476,716     12/19/95     US     US       09/207316     12/19/95     US     US       09/207316     12/17/94     US     US       5,375,766     12/12/91     US     US       5,370,921     7/1/99     US     US       5,672,677     9/30/97     US     US       5,665,461     9/9/907     US     US       5,761,801     6/9/98     US     US       5,718,789     2/17/98     US     US	Dexter	US		1/8/91	4,983,552	Method for Making Organosilazanes
Application     usubor future Date     Status Application     Country Date       Application     1/13/92     Country Application     Country Country       5,154,976     10/13/92     US       5,154,976     10/13/92     US       5,476,716     12/19/95     US       69/207316     12/27/94     US       69/347,091     7/1/99     US       4,992,325     2/12/91     US       5,665,461     9/30/97     US       5,761,801     6/9/98     US	Dexter	US		2/17/98	5,718,789	Method for Making a Debossed Conductive Film Composite
Application     Live Country     Status     Country       Application     1/30/96     US     Country       5,540,963     7/30/96     US     Country       5,154,976     10/13/92     US     US       5,476,716     12/19/95     US     US       69/207316     12/27/94     US     US       69/347,091     7/1/99     US     US       69/347,091     7/1/99     US     US       5,572,677     9/30/97     US     US       5,665,461     9/9/97     US     US       5,861,111     1/19/99     US     US	Dexter	US		86/6/9	5,761,801	Method for Making a Conductive Film Composite*
Application No.     Issue or Fulling Date     Chlank + Aciwel     Column + Column + C	Dexter	US		1/19/99	5,861,111	Method for isomerization of arylpropargyl ether mono- mers and uses therefor
Application     Tsucor Willing     Characterity     Status     Status     Country     Country <thcountry< t<="" td=""><td>Dexter</td><td>Sn</td><td></td><td>79/9/97</td><td>5,665,461</td><td>Low Moisture Absorption Syntactic Foam</td></thcountry<>	Dexter	Sn		79/9/97	5,665,461	Low Moisture Absorption Syntactic Foam
Application No.     Issue or rithing     Chiank = Application No.     Status       5,540,963     7/30/96     US     Status     Country       5,154,976     10/13/92     US     US     US       5,476,716     12/19/95     US     US     US       09/207316     12/27/94     US     US     US       09/347,091     7/1/99     US     US     US       4,992,325     2/12/91     US     US     US       5,370,921     12/6/94     US     US     US	Dexter	US		9/30/97	5,672,677	Long Open Time Polyamide Hot Melt Adhesives
Application     Issue or Fruing     Asian Status       5,540,963     7/30/96     Activel     Chianita       5,154,976     10/13/92     US     US       6,375,766     12/19/95     US     US       09/207316     12/27/94     US     US       09/347,091     7/19/95     US     US       4,992,325     2/12/91     US     US	Dexter	US		12/6/94	5,370,921	Lightning Strike Composite and Process
Application     Issue contributing     Application     Issue contributing     Application     Contributing     Application     Contributing     Application     Contributing     Application     Contributing     Contrib	Dexter	US		2/12/91	4,992,325	Inorganic Whisker Containing Impact Enhanced Prepregs and Formulations
Application No.     Issue or Willing     Application N	Dexter	US		7/1/99	09/347,091	Hydrophobic, High Tg Cycloaliphatic Epoxy Resins
Appleminut     Issue or Willing     Appleminut     County       5,540,963     7/30/96     Appleminut     County       5,154,976     10/13/92     US     US       5,476,716     12/19/95     US     US       09/207316     US     US     US	Dexter	US		12/27/94	5,375,766	Hot Melt Adhesive Spray Dispenser
Application     No.     Issue of Future     Optimize	Dexter	US			09/207316	High Viscosity Polymeric Compositions for Use in Under Filing Flip-Chip for Use in Under Filing
Application No.     Issue or (filing Date     Status Active)       5,540,963     7/30/96     US       5,154,976     10/13/92     US	Dexter	Sn		12/19/95	5,476,716	Flame Retardant Epoxy Molding Compound, Method and Encapsulated Device
Application No. Issue or Wing Status   5,540,963 7/30/96 US	Dexter	US		10/13/92	5,154,976	Flame Retardant Epoxy Molding Compound Method and Encapsulated Device
Application No. Date Scalus   Application No. Date Active)	Dexter	Sn		7/30/96	5,540,963	Expandable Films and Molded Products Therefrom
	Current	9	รับไปได้ อาจีซี ได้ได้ไปไป สิ่ง หนึ่ง เป็น (A. กร้างได้เห็นได้เห	Issue or F()Ing Date		

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	Patent No./	Issue o Frung	Satus (Blank=	County	Current Current
Method of Encapsulating a Semiconductor Device with a Flame Retardant Epoxy Molding Compound	5,041,254	8/20/91		US	Dexter
Method of Manufacture Preforms*	4,758,398	7/19/88		US	Dexter
Method of Mixing Mold Release Agents	5,399,310	3/21/95		US	Dexter
Monolithic Expandable Structures, Methods of Manufac- ture and Composite Structures	(Not yet assigned)	7/21/00		US	Dexter
Methods of Reducing the Chloride Content of Epoxy Compounds	09/578,785			sn	Dexter
Multilayer Composite Article Containing a Multimodal Combination of Filler Particles	5,397,618	3/14/95		Sn	Dexter
Circuit Boards	4,994,316	2/19/91		Sn	Dexter
Oriented Expanded Molded Products	5,660,901	8/26/97		US	Dexter
Perfluorinated Hydrocarbon Polymer-Filled Adhesive Formulations and Uses Therefor	5,717,034	2/10/98		US	Dexter
Polyimide with Reduced Anhydride Content*	5,175,241	12/29/92		US	Dexter
Process of Making a Lightning Strike Composite	5,470,413	11/28/95		Sn	Dexter
Reducing Void Formation in Curable Adhesive Formula- tions	09/317,493			US	Dexter
Semiconductor Device Encapsulated with a Flame Retar- dant Epoxy Molding Compound	5,413,861	5/9/95		Sn	Dexter
Silver-glass paste for attachment of silicon die to ceramic substrates	4,636,254	1/13/87		Sn	Dexter
Thermosetting resin compositions containing maleimide and/or vinyl compounds	6,034,195	3/7/00		US	Dexter

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Adhesive Paste Containing Polymeric Resin	Solvent free die-attach compositions*	Silver-glass die attach paste with reduced resin	Resinless pseudoplastic bonding compositions	Resinless pseudoplastic bonding compositions	Reducing Void Formation in Curable Adhesive Formula- tions	Manually operable die attach apparatus	Low Temperature Glass With Improved Thermal Stress Properties and Method of Use	Low temperature glass paste with improved thermal stress properties	Low Temperature Glass Paste With High Metal to Glass Ratio	Freeze resistant die-attach compositions*	Die-attach composition comprising polycyanate ester monomer	Die adhesion testing method and apparatus	Adhesive bonding composition with bond line limiting spacer system	Waterborne Epoxy Derived Adhesive Primers	Waterborne Epoxy Derivative Composition	Toughened Prepregs and Formulations	
5,391,604	5,447,988	4,968,738	5,306,333	5,403,389	08/781,995	5,336,357	5,334,558	5,543,366	5,663,109	5,489,641	5,358,992	5,313,841	5,232,962	5,266,611	5,378,740	5,002,821	Patenting/
2/21/95	9/5/95	11/6/90	4/26/94	4/4/95	1/697	8/9/94	8/2/94	8/6/96	9;2/97	2/6/96	10/25/94	5/24/94	8/3/93	11/30/93	1/3/95	3/26/91	Issue of Fung
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SN	US	ß	Sn	Sn	US	US	US	US	US	US	us	US	US	Sn	S	US	
Dexter	Dexter	Dexter	Dexter	Dexter	Dexter	Dexter	Dexter	Dexter	Dexter	Dexter	Dexter	Dexter	Dexter	Dexter	Dexter	Dexter	Current

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Dexter	US		8/2/88	4,761,224	Silver-glass paste with paste with poly-modal flake size distribution and quick dry vehicle
Dexter	US		2/3/98	5,714,086	Propargyl Ether-containing Compositions Useful for Underfill Applications
Dexter	US		6/29/98	09/107,897	Maleimide Containing Formulations and Uses Therefor
Dexter	U <b>s</b>		8/4/98	5,789,757	Maleimide Containing Formulations and Uses Therefor
Dexter	US		7/28/99	09/362,809	Low Viscosity Acrylate Monomer Formulations Contain- ing Same and Uses Therefor
Dexter	US		9/2/97	5,663,109	Low temperature Glass Paste with High Metal to Glass Ratio
Dexter	US		5/24/99	09/317,493	Elimination of Voids in Moisture Absorbing Boards by Use of Low Temperature Cure
Dexter	US		1/6/97	08/781,995	Elimination of Voids in Moisture Absorbing Boards by Use of Low Temperature Cure
Dexter	US		5/19/98	5,753,748	Bleed Resistant Cyanate Ester-containing Compositions
Dexter	US		7/8/97	5,646,241	Bleed Resistant Cyanate Ester-containing Compositions
Dexter	US		9/22/97	08/935,352	Acrylate Containing Formulations and Uses Therefor
Dexter	US		4/14/92	5,104,604	Method of Encapsulating a Semiconductor Device with a Flame Retardant Epoxy Molding Compound
Dexter	S		8/16/94	5,338,781	Flame Retardant Epoxy Molding Compound, Method and Encapsulated Device, Method of Encapsulating a Semi- conductor Device with a Flame Retardant Epoxy Molding Compound
Dexter	US		5/30/95	5,420,178	Flame Retardant Epoxy Molding Compound
		Status (Blank Active)	Tsucor Filing	Patent No.	

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00 Reline Active Co		194	
(Blank = US		3/7/00	Issue of Fully Date
S.			
		US	Count

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